



From Tip to Tail: Solving Defense Aircraft Test Challenges

Tuesday, May 24th – 2:30pm

Brandon Treece, NI

Eric Metzler, Viewpoint Systems

Jennifer Platt, Tech 180

From Tip to Tail: Solving Defense Aircraft Test Challenges

Brandon Treece

Chief Solutions Marketing Manager

Electronics Test, Defense Aircraft

Aerospace, Defense, and Government

NI





NI and Aircraft Test

Design | Validate | Produce | Maintain

Minimize schedule risk

Maximize quality & reliability

Maintain *and* Modernize infrastructure





NI and Aircraft Test

Design | Validate | Produce | Maintain

Electrical & Mechanical

Test and simulate hundreds of systems to ensure reliable operation across all mission scenarios

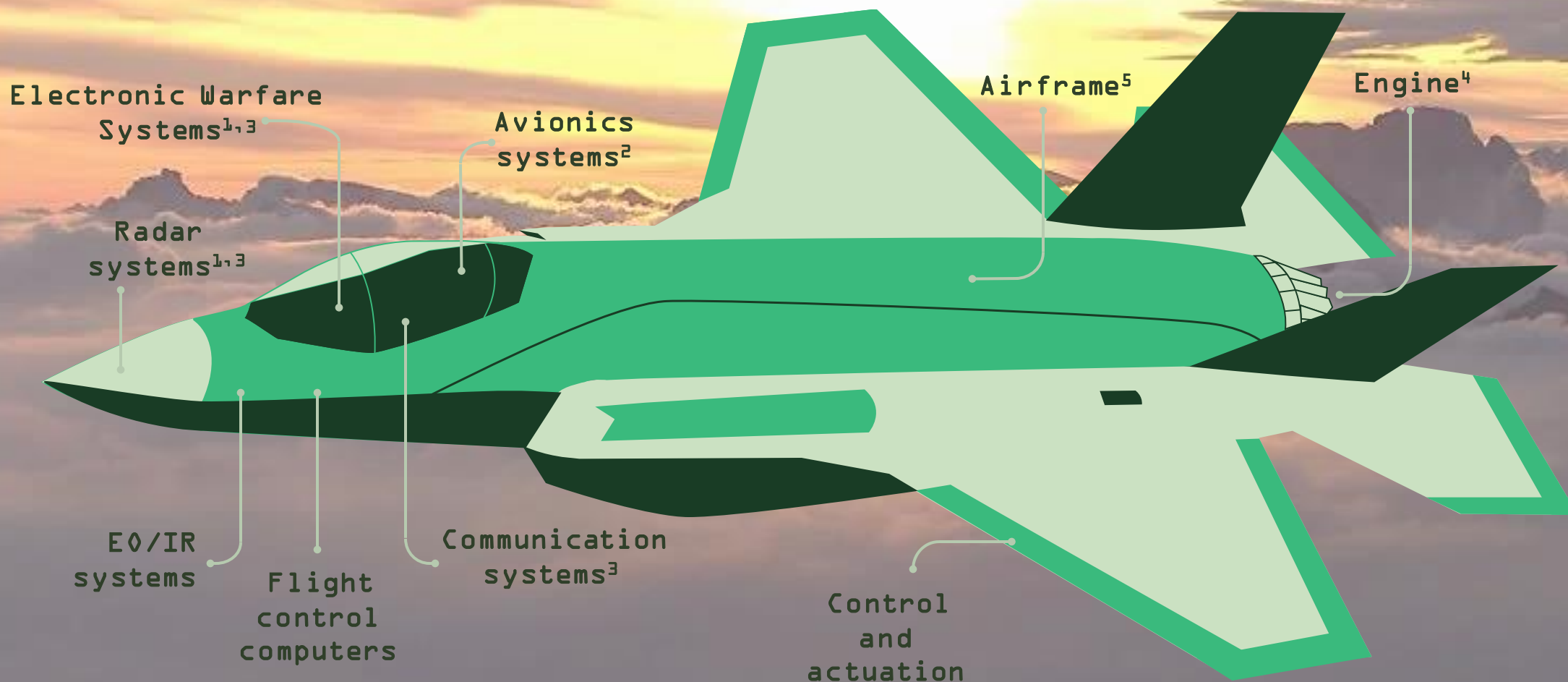
Radar & Electronic Warfare

Ensure reliable operation in an increasingly contested and congested electromagnetic spectrum

Communication, Navigation, & Surveillance

Operate military navigation, telemetry, and datalinks while coexisting with commercial systems

NI and Aircraft Test



¹Solving the Latest Challenges for Testing Electronically Scanned Arrays - Tuesday @ 3:30

²Digital Avionics Interface Selection - Simplifying a Not So Simple Choice - Wednesday @ 9:00

³Rapidly Prototyping Cognitive RF Systems - Wednesday @ 10:15

⁴Testing Propulsion Systems Across the Aerospace Industry - Wednesday @ 11:00

⁵Deploy Static and Fatigue Structural Test Systems with COTS Tools - Aerospace Pavilion

Addressing Challenges of FPA Test

Eric Metzler
System Architect
CLA, CTA, CPI
Viewpoint Systems





Aedis Framework



FPA and Electronics Payload Emulation

Eric Metzler
System Architect
CLA, CTA, CPI
Viewpoint Systems

Carl Kosmerl
John Farnach
emetzler@viewpointusa.com

ni EO/IR System Landscape by Mission

ni.com

Remote Sensing



Night Vision



*Rangefinding/
Designation*



ISR



IRST



IR Homing



Laser & IR Targeting

Electronic Warfare



IR Threat Warning



Laser Threat Warning



Laser / IR Countermeasures

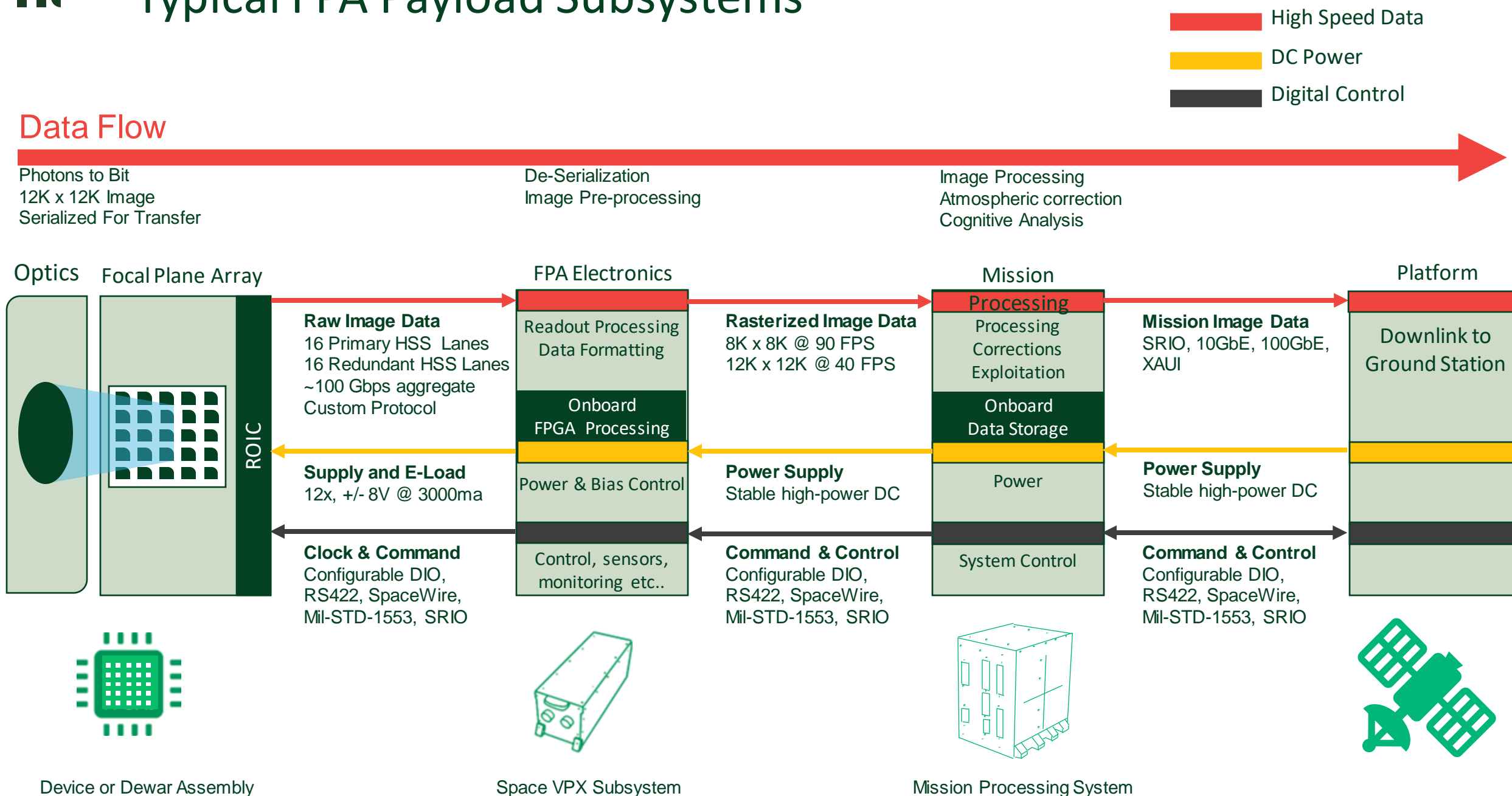


Directed Energy



Typical FPA Payload Subsystems

Data Flow



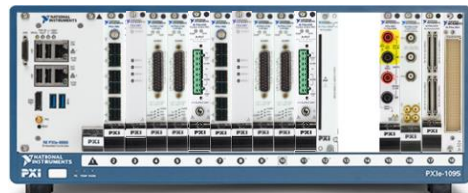
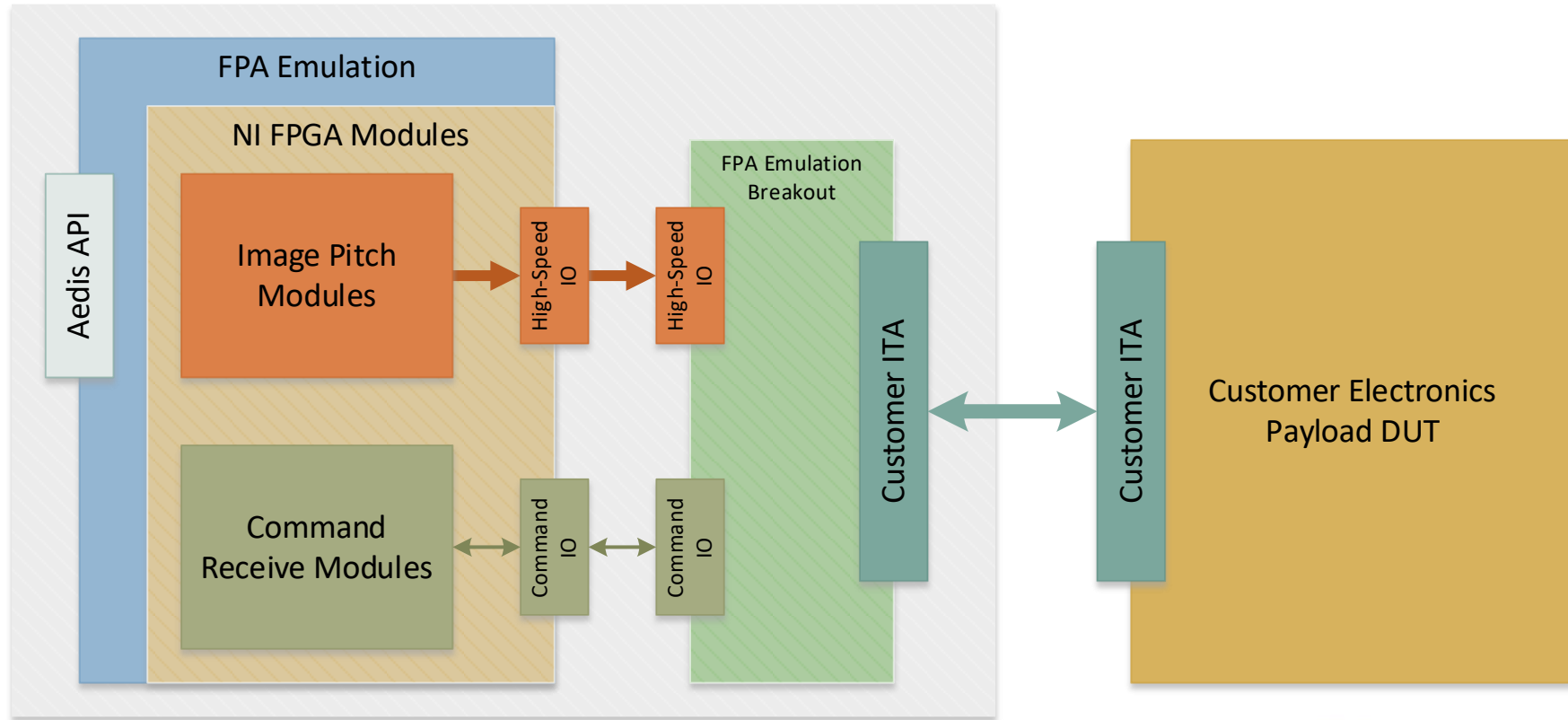
Key Challenges

- FPA testing/emulation is hard
 - High data rates/determinism
 - *Unique interfaces*
 - *Specialized hardware*
 - *No COTS test systems exist*
- Incomplete requirements
- Short, inflexible schedules
- Predetermined budgets

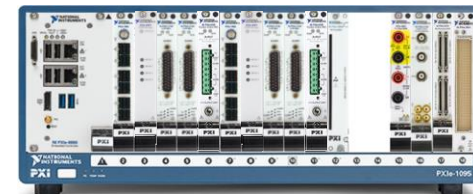
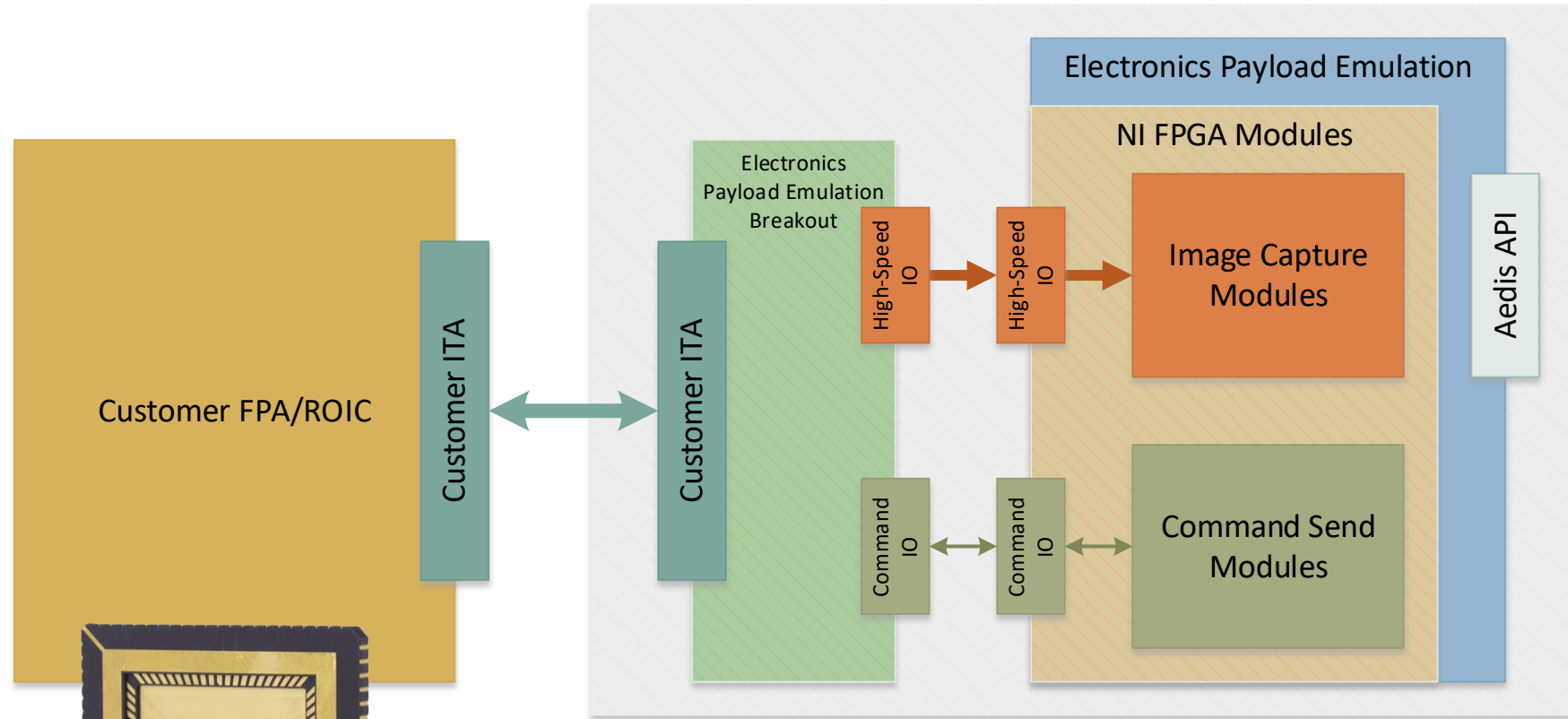
How is Aedis solving these problems?

- **Reduced development time**
 - Core set of customizable software components
 - Pre-built buffer electronics minimizes customization for specialized interconnects
- **Extendable architecture**
 - Allows for different sized sensor interfaces and IO count
 - Allows for unique customer processing in software
- **Validation readiness**
 - Hardware provides transmit and receive pathways
 - Complementary software modules for validating delivered system
 - Loopback capable
- Bridges the gap to complete requirements by providing pre-made solutions to common problems

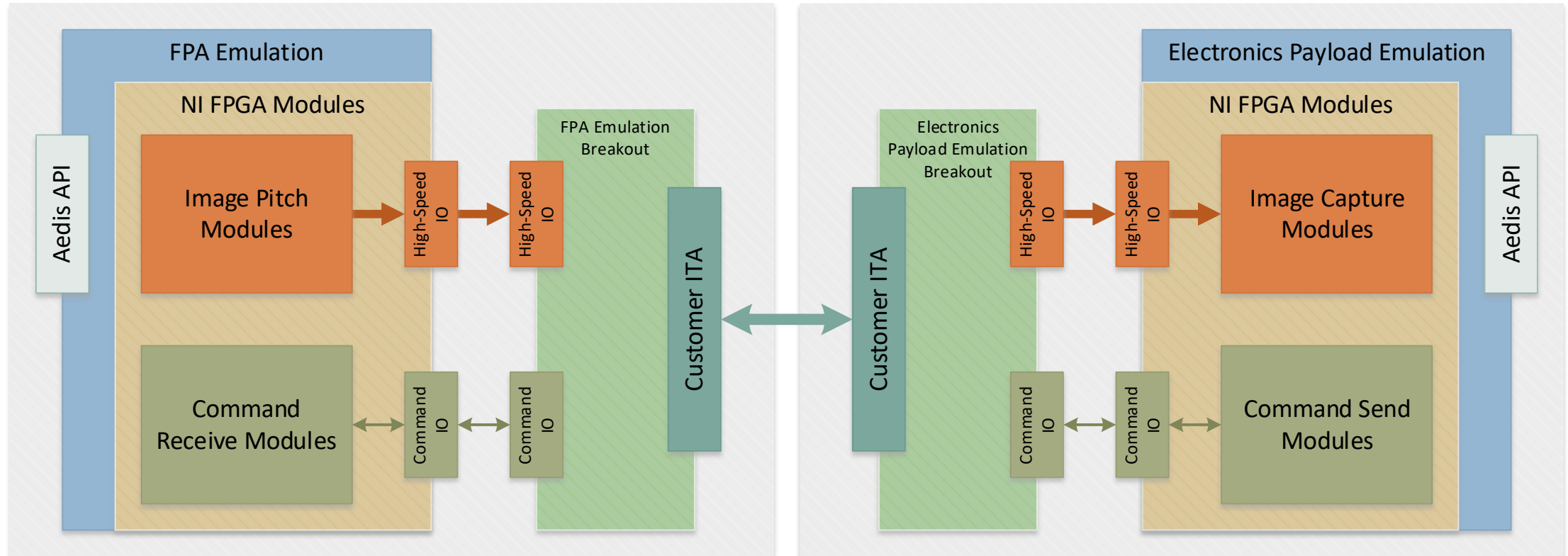
Aedis FPA Emulation Overview

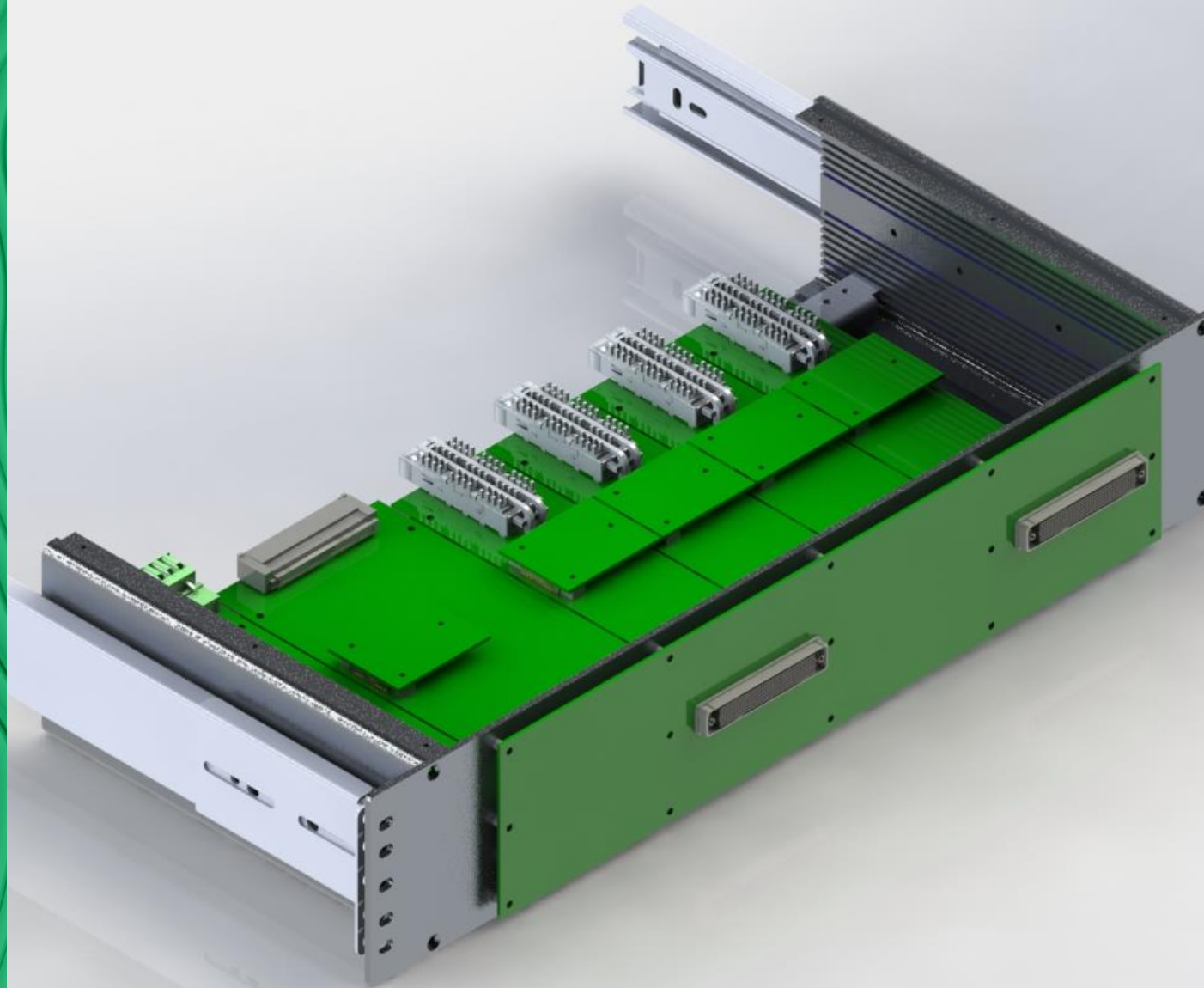


Aedis Electronics Payload Emulation Overview



Aedis Validation Overview





Interface Breakout

- NI interface to customer mass interconnect
- Modular electronics selected for application
- High-speed, full duplex signal buffering
 - LVDS
 - SERDES/CML
- Software configurable buffer control (per-channel)
- Test point access
- Power supply and load profiling

Aedis Software Overview

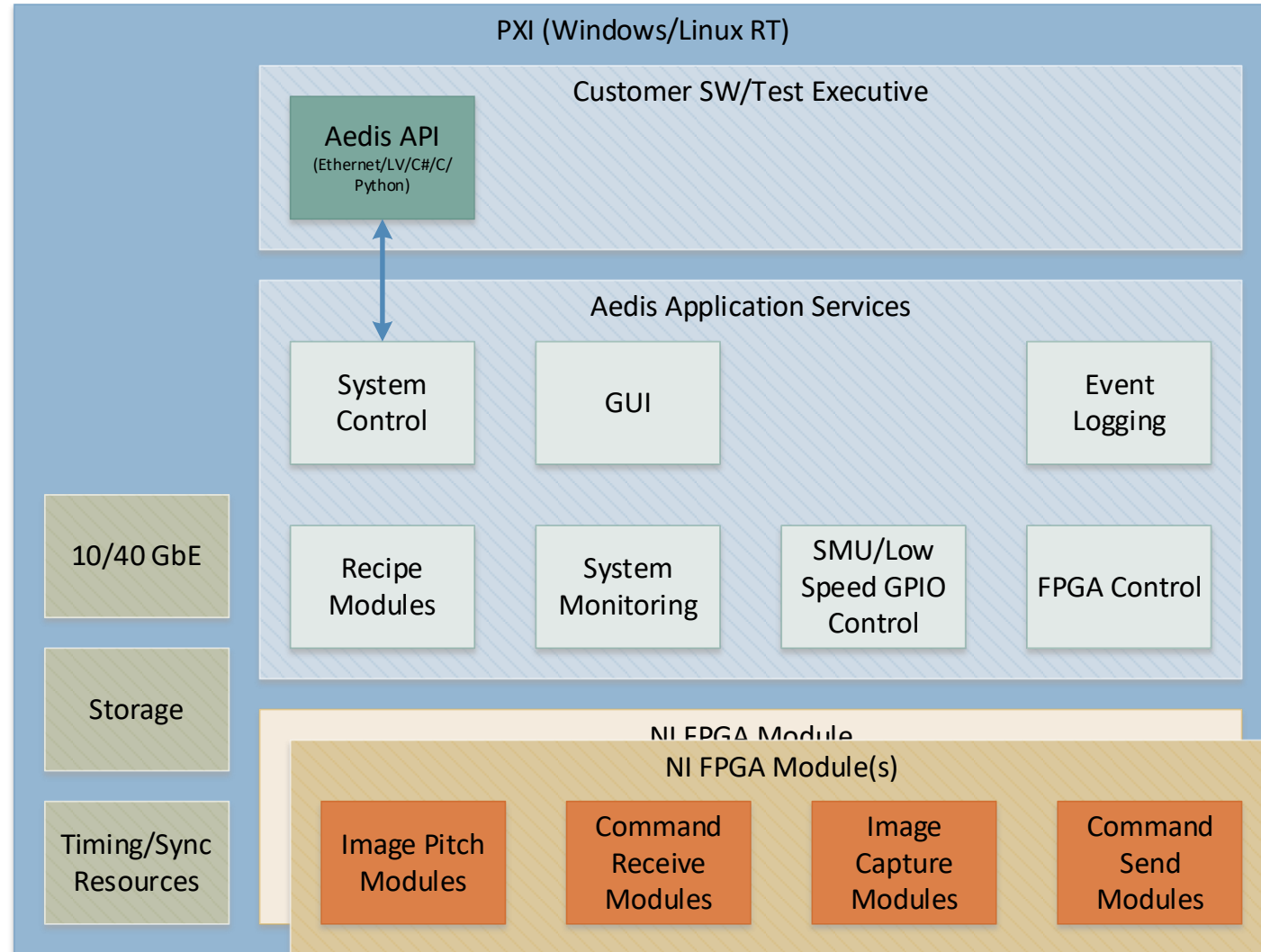


Image Pitch Modules

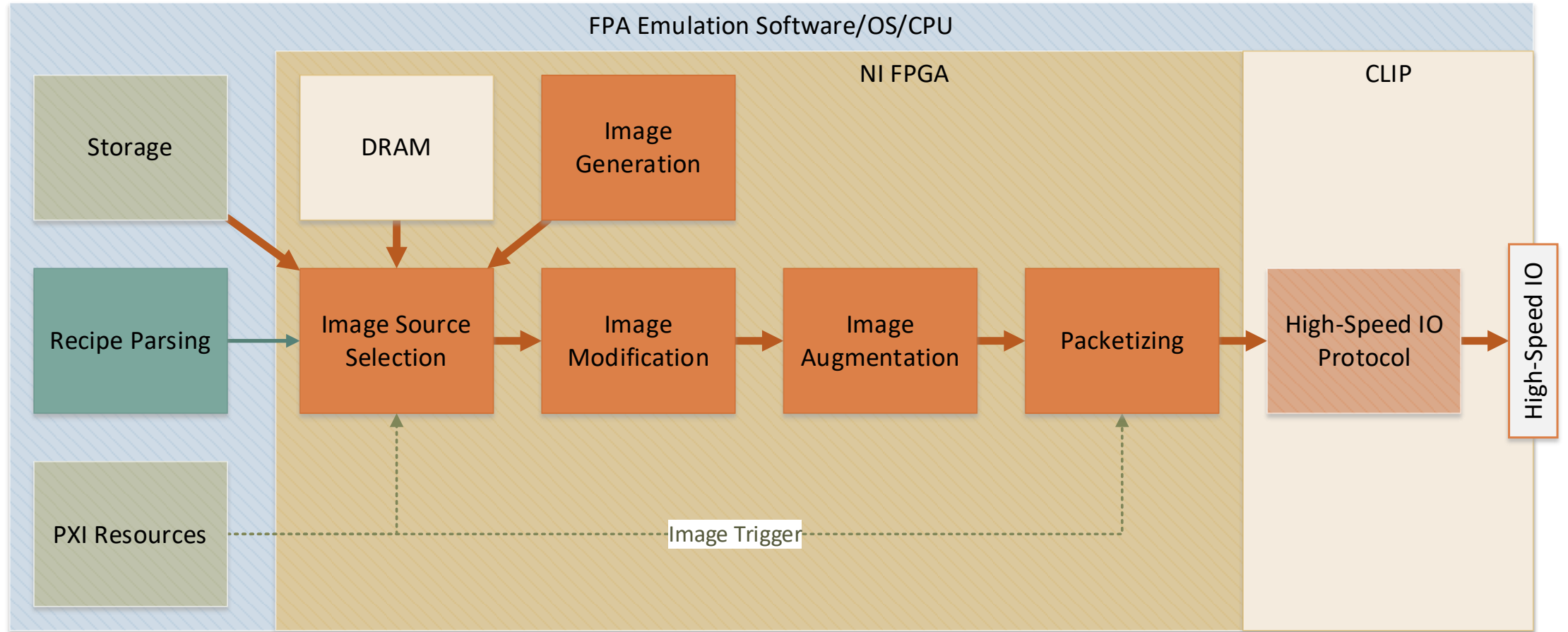
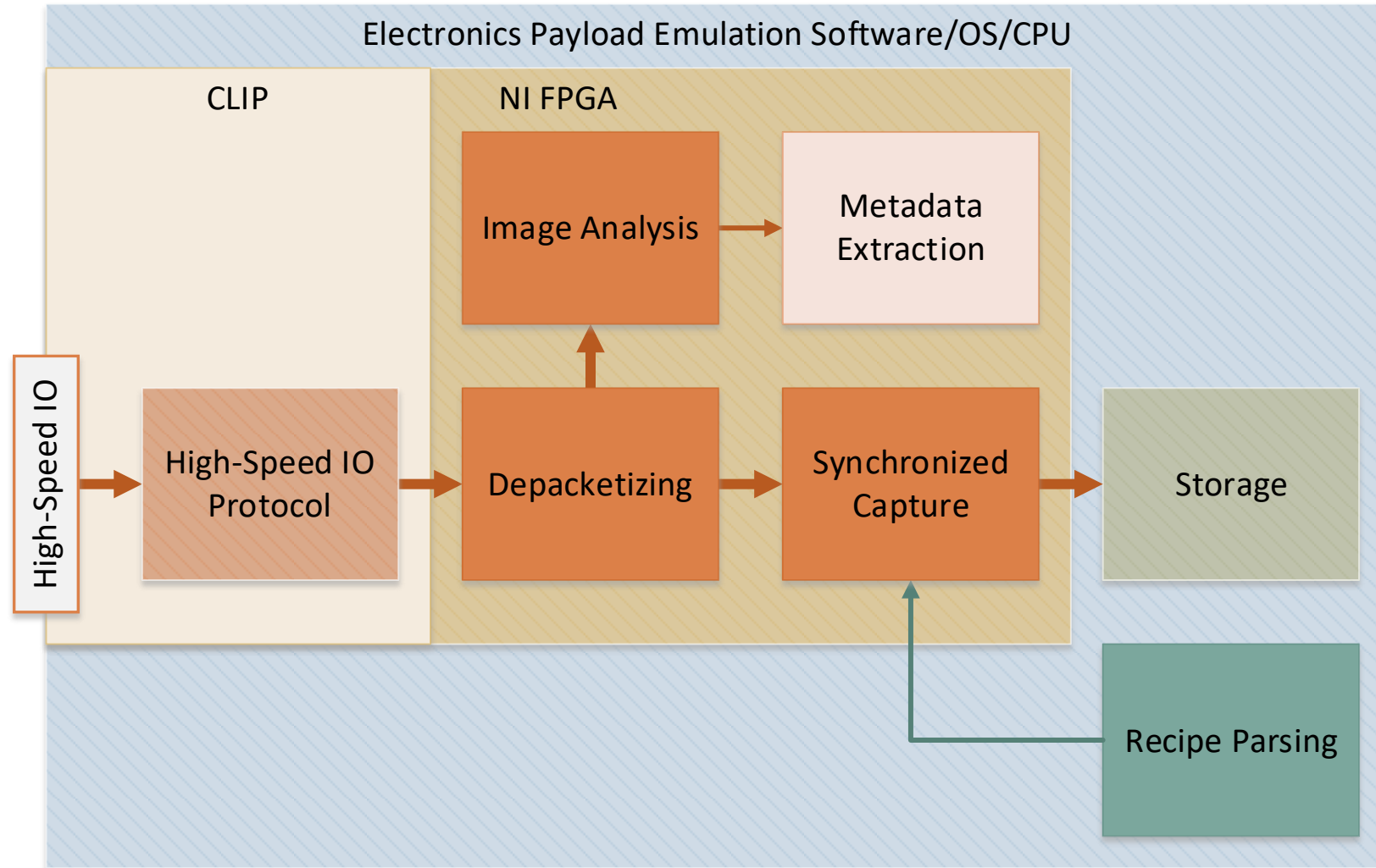
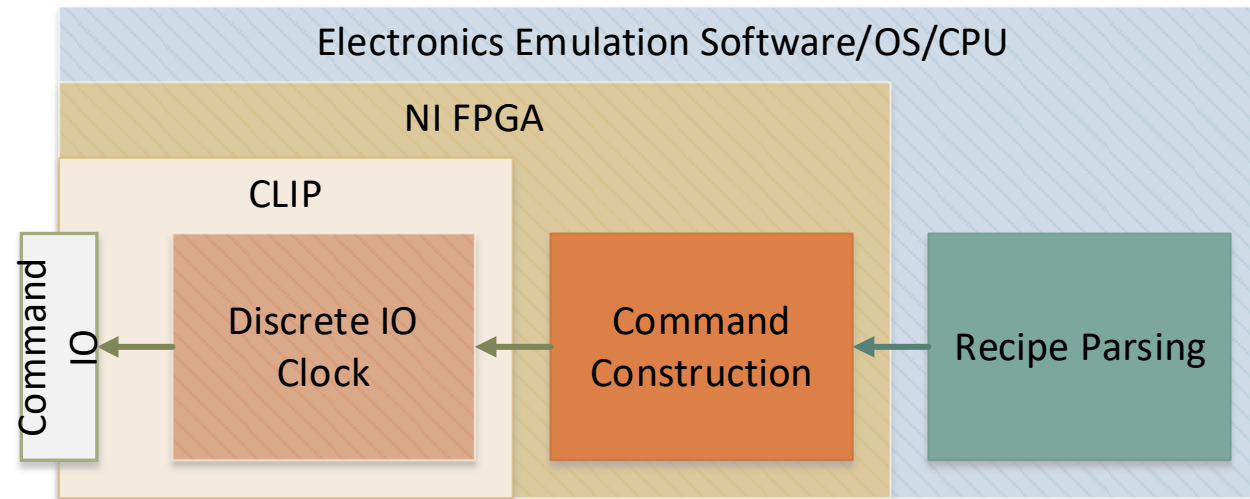


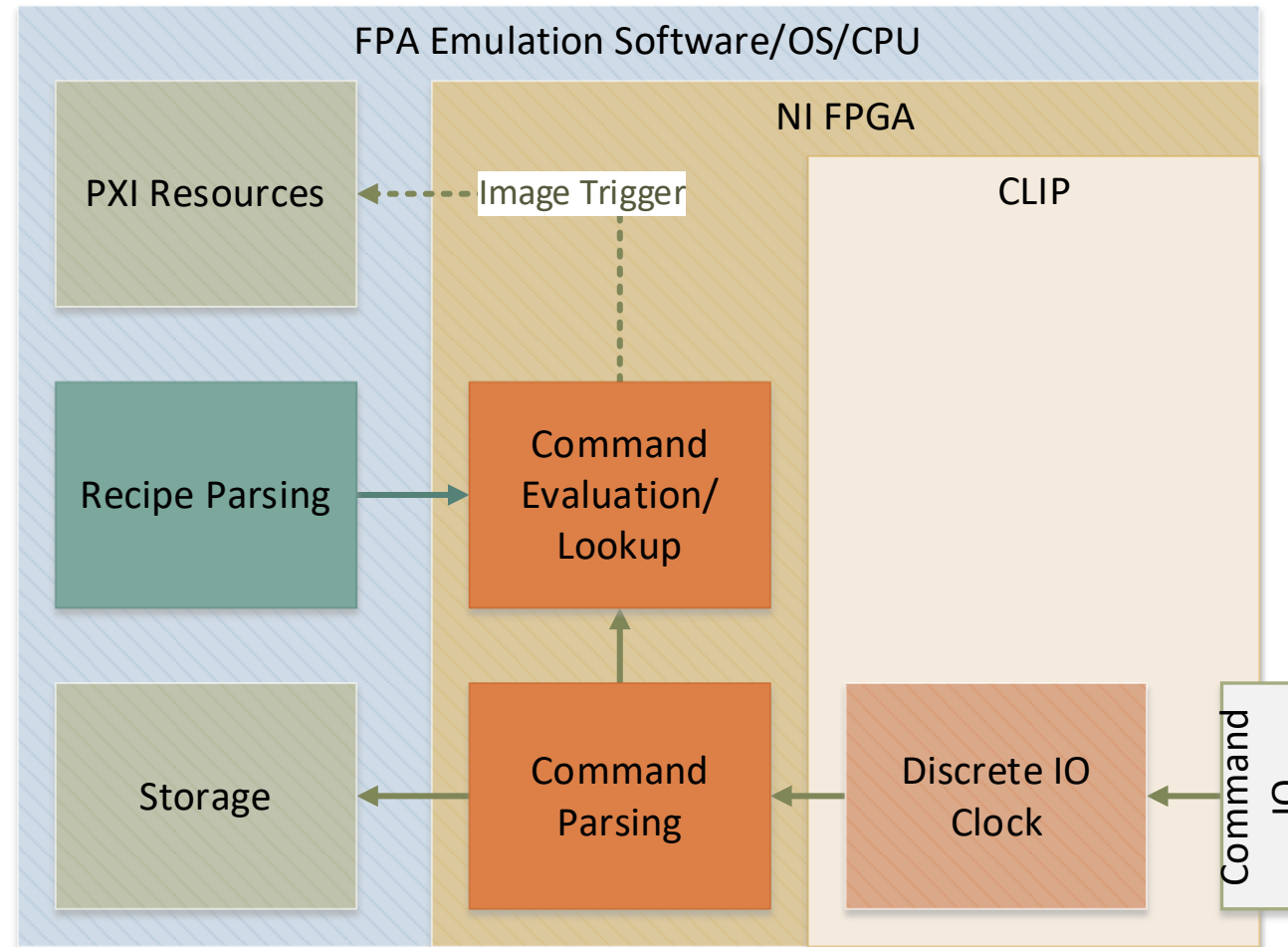
Image Capture/Analysis Modules



Command Send Modules



Command Receive Modules



Benefits and Contact

- Reduced development cost and time
- Expandability
- Extensibility
- Isolation of components for unit testing
- Ease of verification

emetzler@viewpointusa.com

linkedin.com/company/viewpoint-systems/

viewpointusa.com/tm/wp/digital-imaging-emulator-approach/

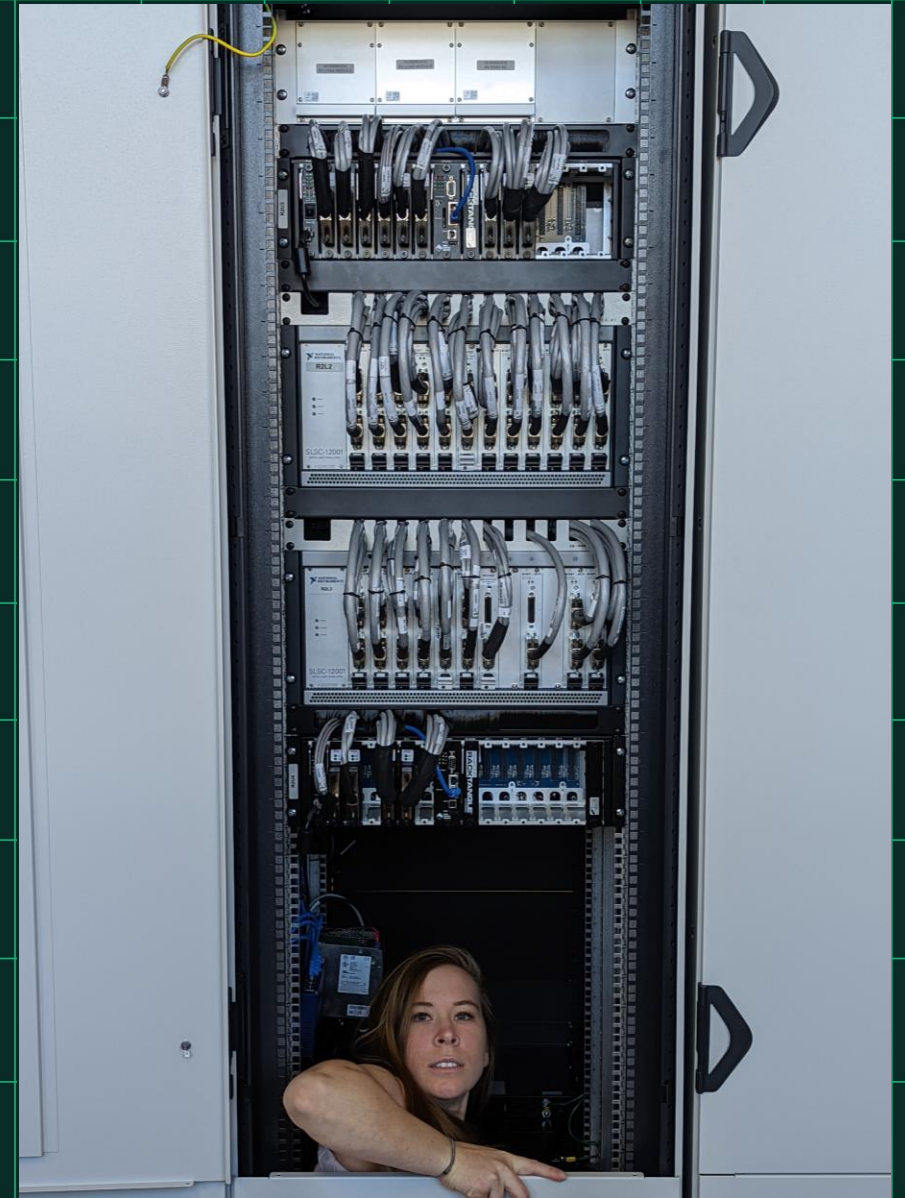


Platinum
Partner



Addressing Challenges of LRU Test

Jennifer Platt
Lead Solution Engineer
Tech180



System-On-Demand (SoD)

Solving Complex Challenges
in LRU Test

Jennifer Platt
Tech180
Systems Engineer





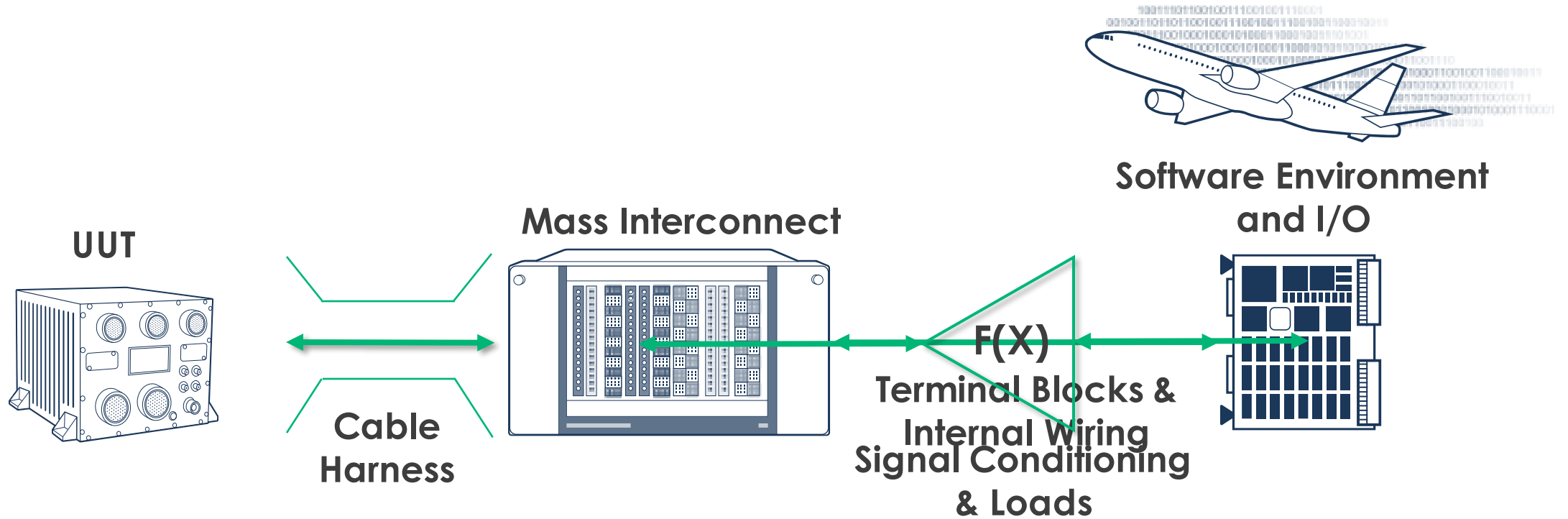
Overview

- What is System-on-Demand?
 - LRU test and SoD architecture
 - Key benefits
- How does System-On-Demand solve challenges in today's LRU market?
 - Single program schedule
 - Multiple lab integration

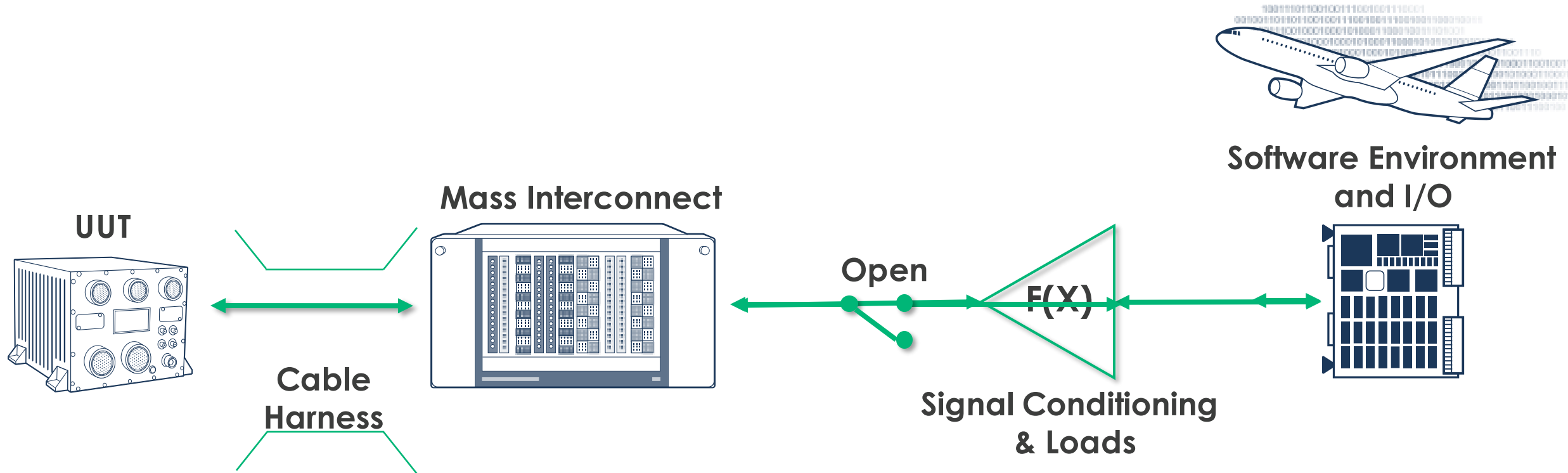
What is System-On-Demand?

- Powerful, flexible architecture built on NI PXI and SLSC platforms
- Supported by an automated toolchain and standardized parts

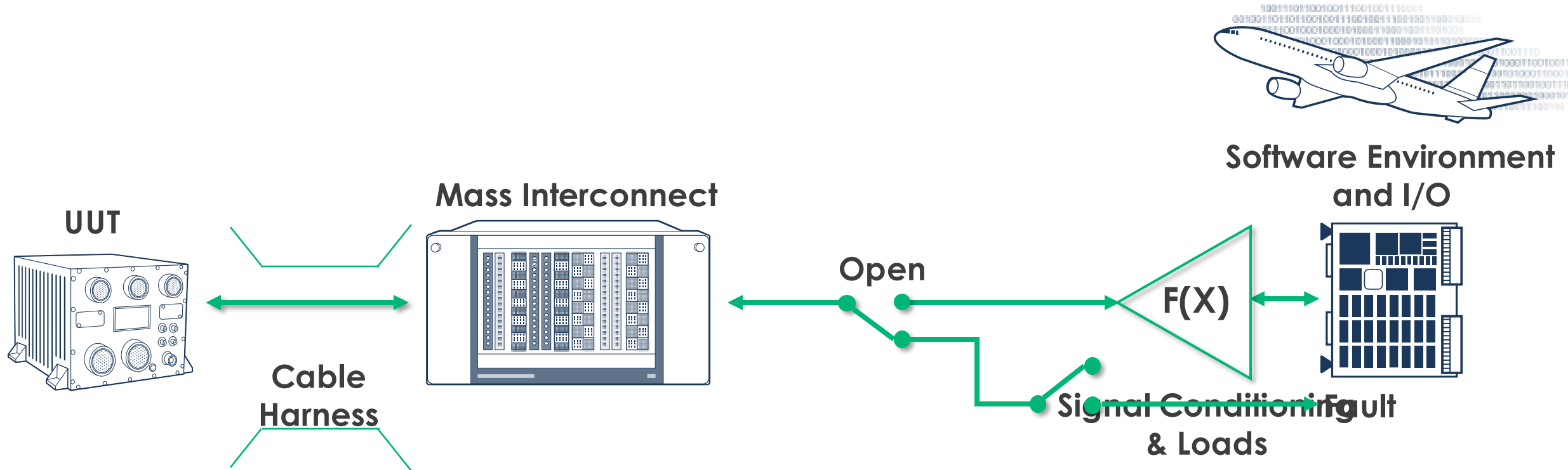
LRU Test Architecture



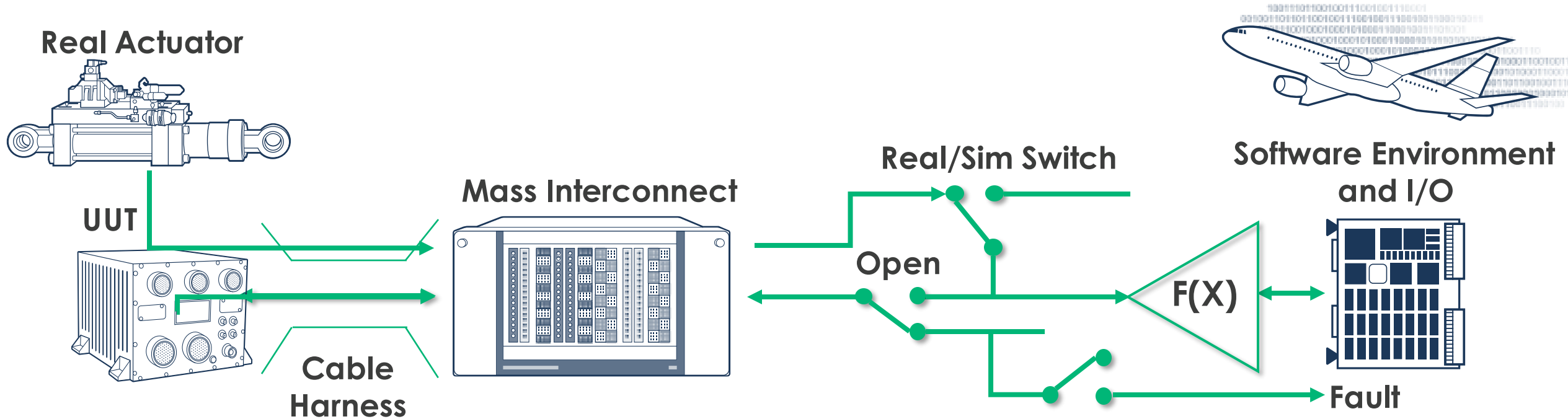
LRU Test Architecture



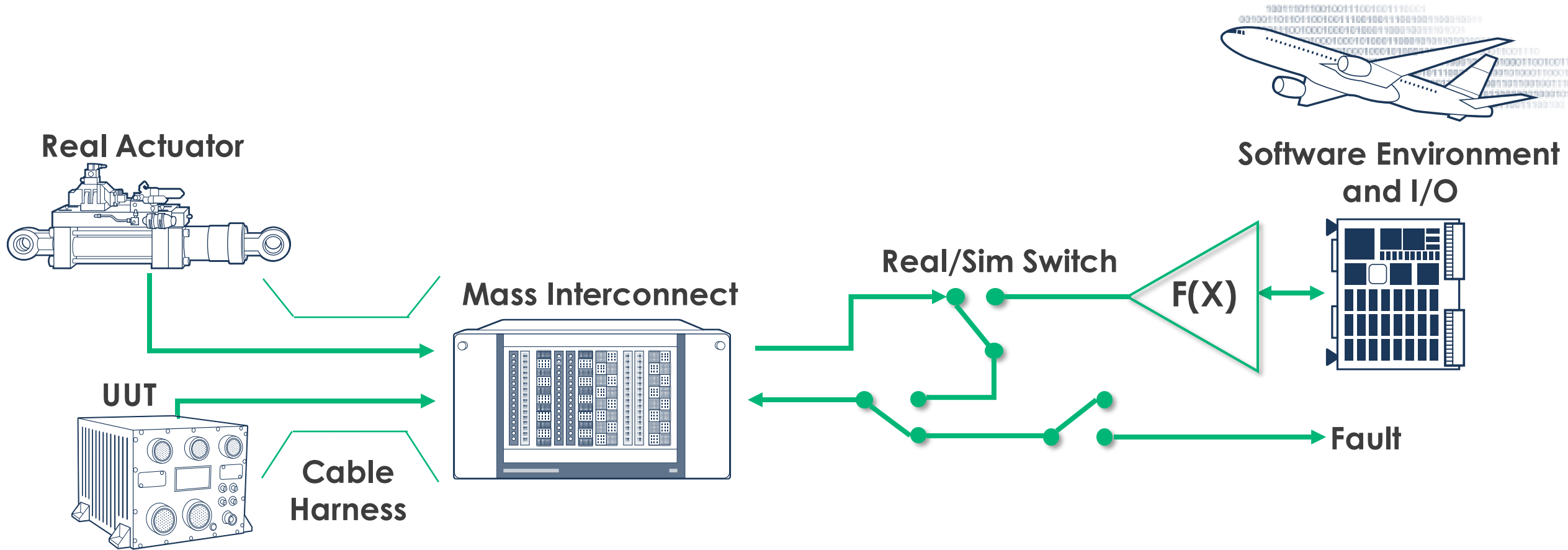
LRU Test Architecture



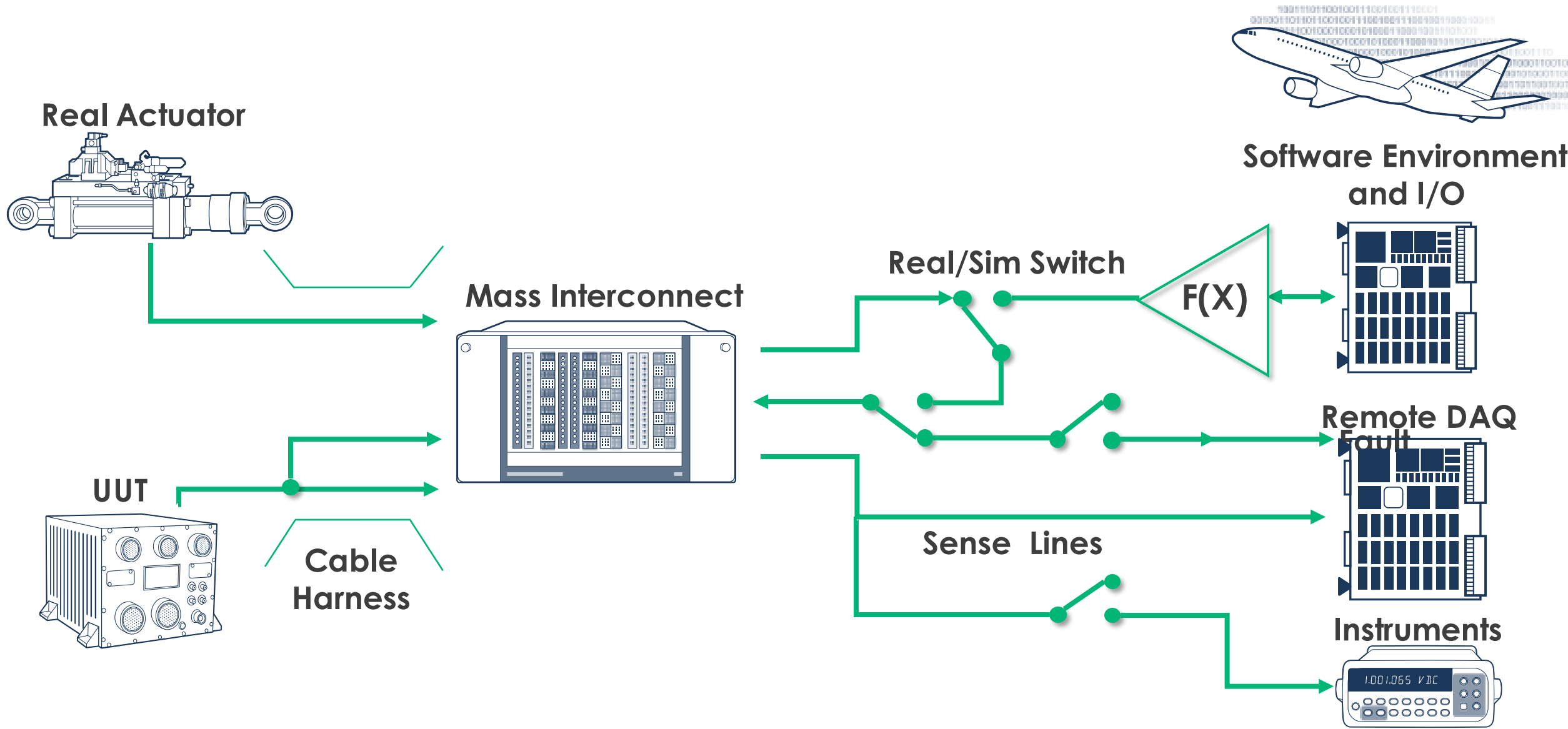
LRU Test Architecture



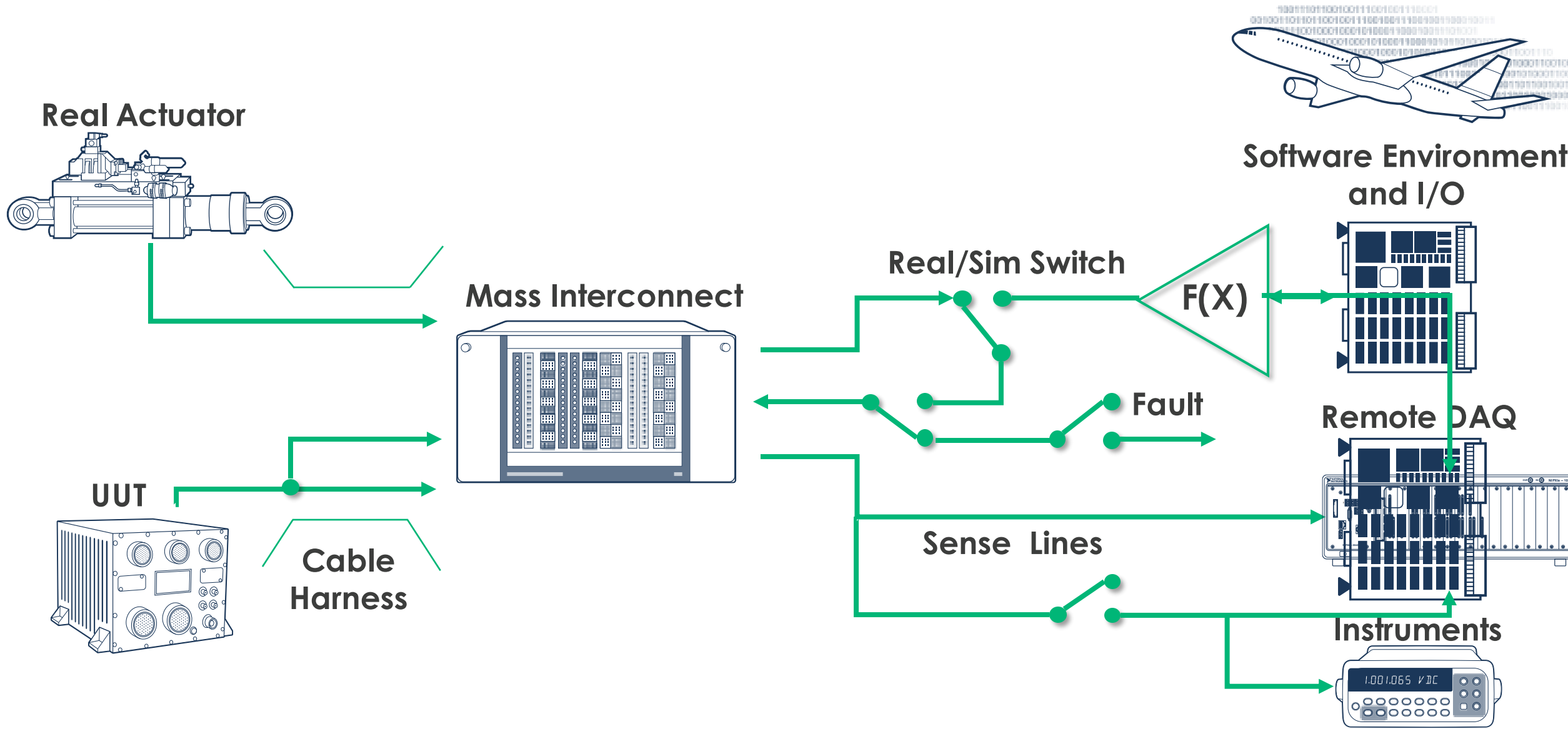
LRU Test Architecture



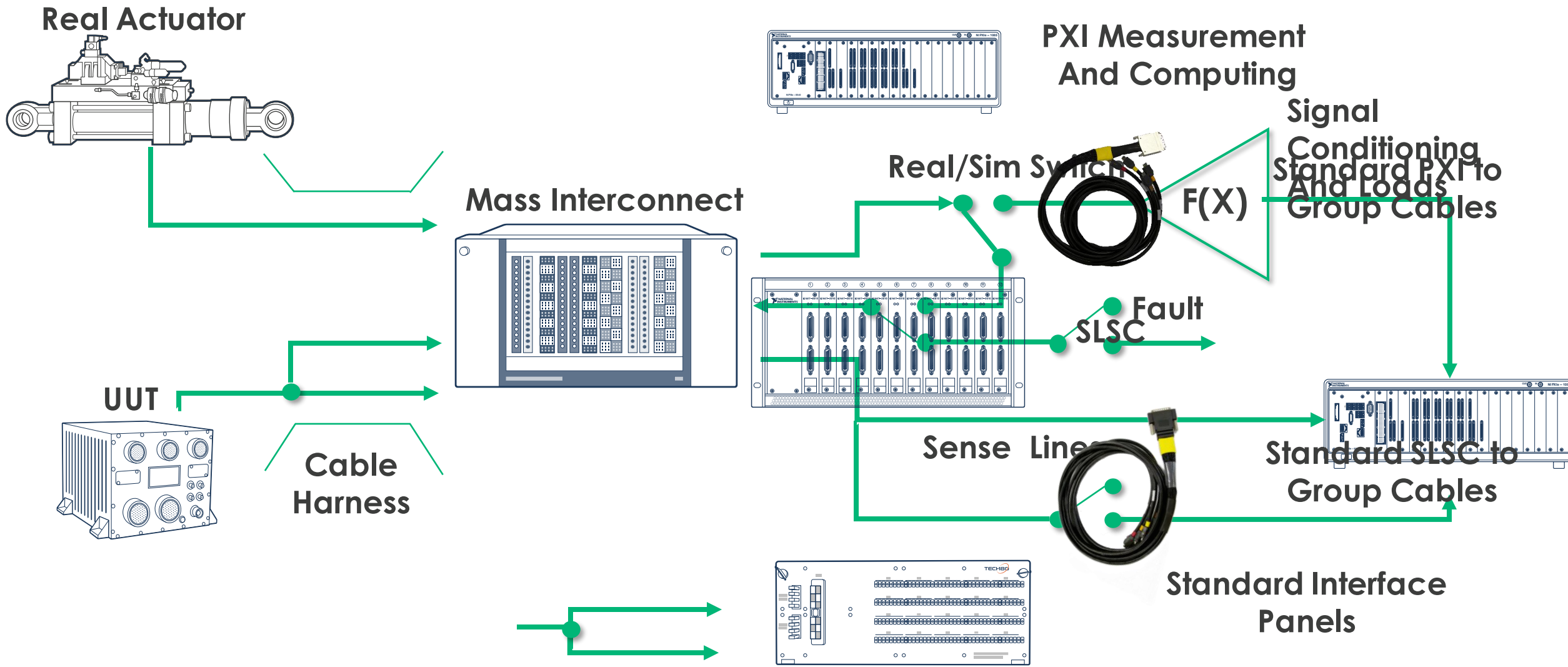
LRU Test Architecture



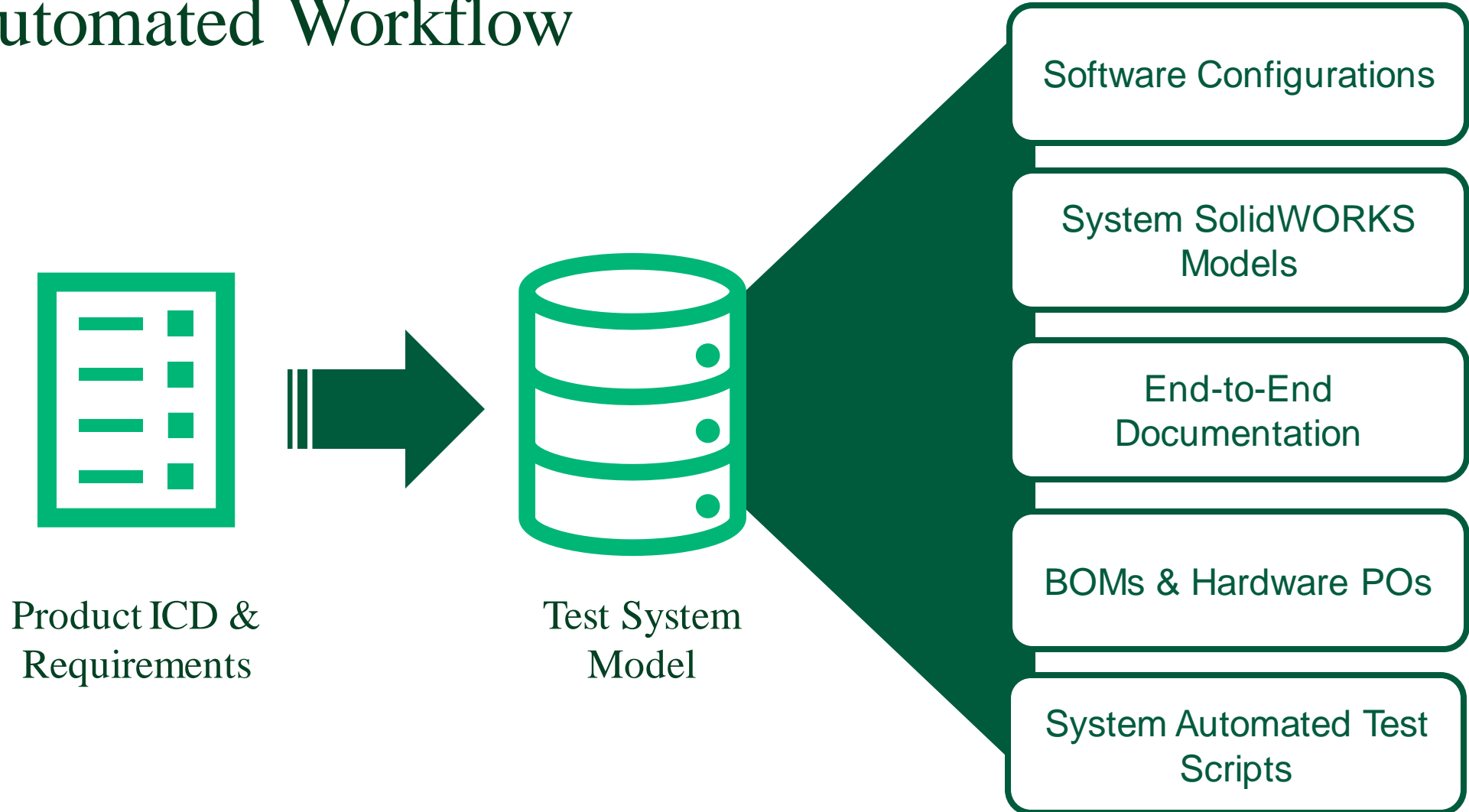
LRU Test Architecture



LRU Test Architecture



Automated Workflow



Standard Signal Library



TECH180
ELECTROMECHANICAL
TEST COVERAGE CATALOG

4.3 BI-DIRECTIONAL
4.3.102 RS-422/RS-485 FULL DUPLEX

COMMUNICATIONS 4

REQUIREMENTS COVERAGE

3.1 INPUT to UUT
3.1.106 INPUT 3-WIRE POTENTIOMETER

SPECIALIZED SENSORS 3

2.2 OUTPUT from UUT
2.2.400 ISOLATED OUTPUT CURRENT +/-20mA

ANALOG 2

1.2 OUTPUT from UUT
1.2.300 OUTPUT DISCRETE HIGH SIDE DRIVER

DISCRETE / DIGITAL 1

REQUIREMENTS COVERAGE

The UUT drives a signal on Pin A that requires a connection to ground through a load.

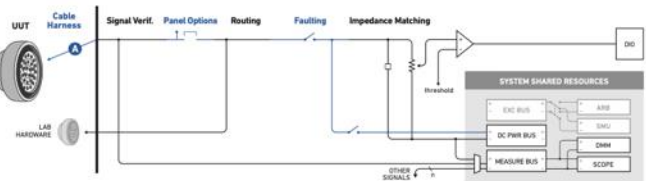
SPECIFICATIONS

In/Output Impedance	24 kΩ
Overvoltage Protection	+/-60V

SPECIFICATIONS

	+/-20 mA	+/-40 mA
In/Output Impedance	92 Ω	92 Ω
Overvoltage Protection	30V	30V
Accuracy	0.13%	0.13%
Resolution	16 bits	16 bits
Max Update Rate	250 kS/s	250 kS/s

SCHEMATIC



CONFIGURATION OPTIONS

Signal Verification

- Instrumentation mode
- Continuous monitoring

Routing

- Passthrough

Faulting

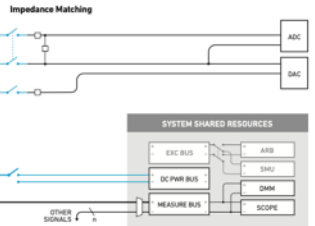
- Open faulting
- Bus faulting
- Line faulting

Impedance Matching

- Series impedance
- Parallel impedance

CONFIGURATIONS

Impedance	25 mΩ
Output Current	20 mA
Overvoltage Protection	25V
Accuracy	0.091%
Resolution	16 bits
Max Update Rate	250 kS/s



Impedance Matching
Series impedance
Parallel impedance

Type Options
Transformer type
Shared excitation (lines A, B needed only once per excitation signal)

Impedance Matching
Series impedance
Parallel impedance

Impedance Matching
Series impedance
Parallel impedance

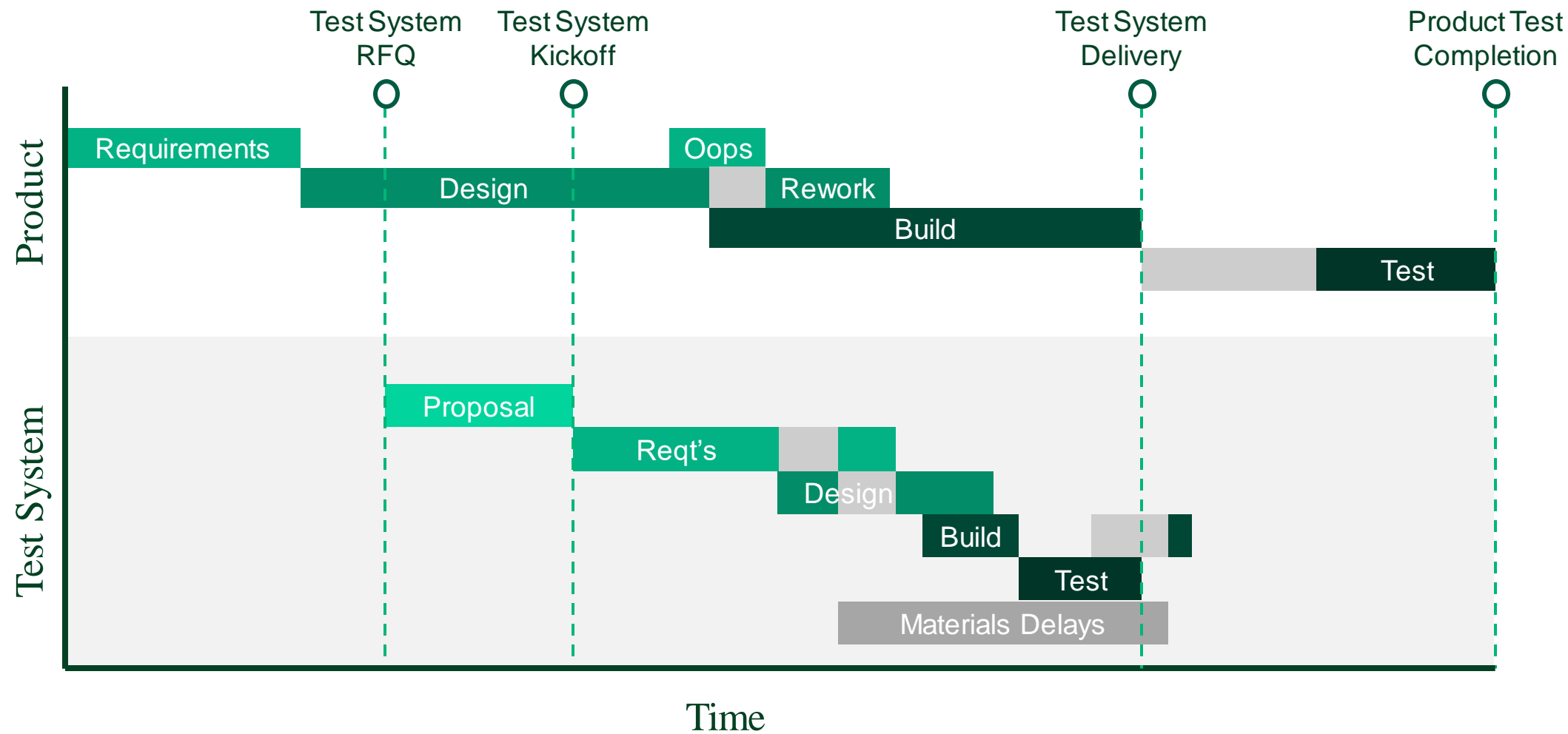
SoD Key Architecture Benefits

- 6 Routing Endpoints
 - Simulation
 - Open/Short/Line Fault
 - Load
 - Real/Sim
 - Parallel DAQ
 - Multiplexed Instrumentation
- Modular Architecture
- Commercial-Off-The-Shelf (COTS) Components
- Automated MBSE Workflow
- Signal Type Library

SoD in a Single Program

- Schedule
- Deliverables
- Maintainability

The Project Schedule

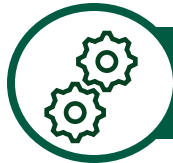


Requirements Discovery & System Design



Lengthy Requirements Discovery Period

- Pre-validated signal types allows for fast requirements mapping
- Modular architecture “black boxing”



Requirements Churn

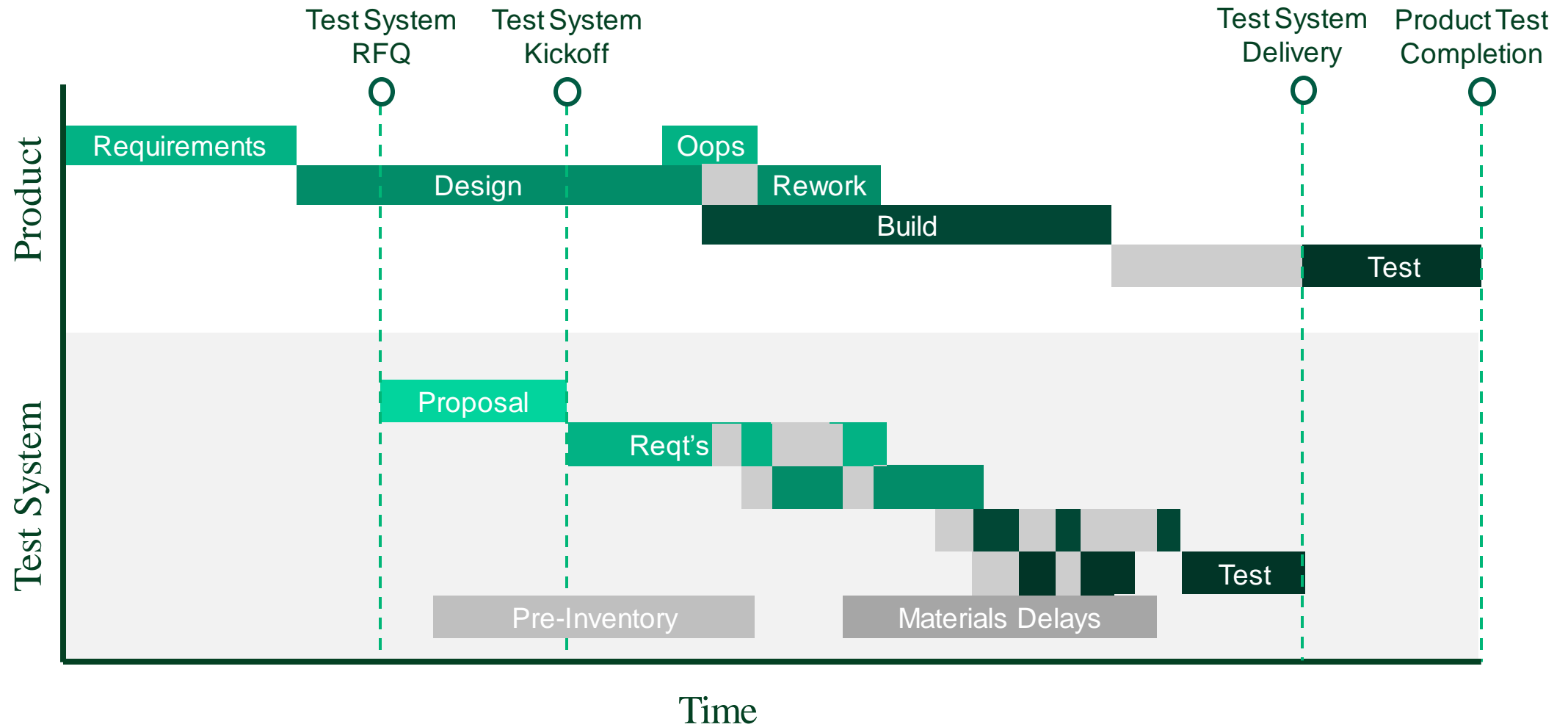
- Automated workflow allows for quick integration of requirements changes into the system



Materials Lead Times

- COTS components and standard types means that most system hardware is already known and can be stocked or ordered immediately, saving weeks of schedule

The Project Schedule



System Build & Validation



Documentation and Software Configurations

- Tedious software configurations, switch command sets, and assembly documents can be generated directly from the test system model



Validation of Test System Prior To Shipment

- Multiplexed instrumentation endpoint allows each signal to be directed to high fidelity instrumentation
- Software test scripts for requirements validation scripted directly from model to automatically exercise signal through fault conditions and expected behaviour
- Boilerplate validation scripts based on standard signal types and faulting implementations

UUT Integration & Obsolescence



Integration with Existing Toolchains

- IO server abstraction layer allows integration with existing software test script infrastructure
- Automated software generation allows software integration prior to delivery



System Capability Upgrades

- Modular approach and built-in signal endpoints allows easy addition of new signals or additional faulting or measurement capabilities



Parts Going End-Of-Life

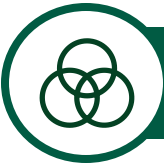
- Easy integration of new hardware into modular architecture allows for for/fit/function upgrades to systems if products reach the end of their lifecycle

SoD over Multiple Labs



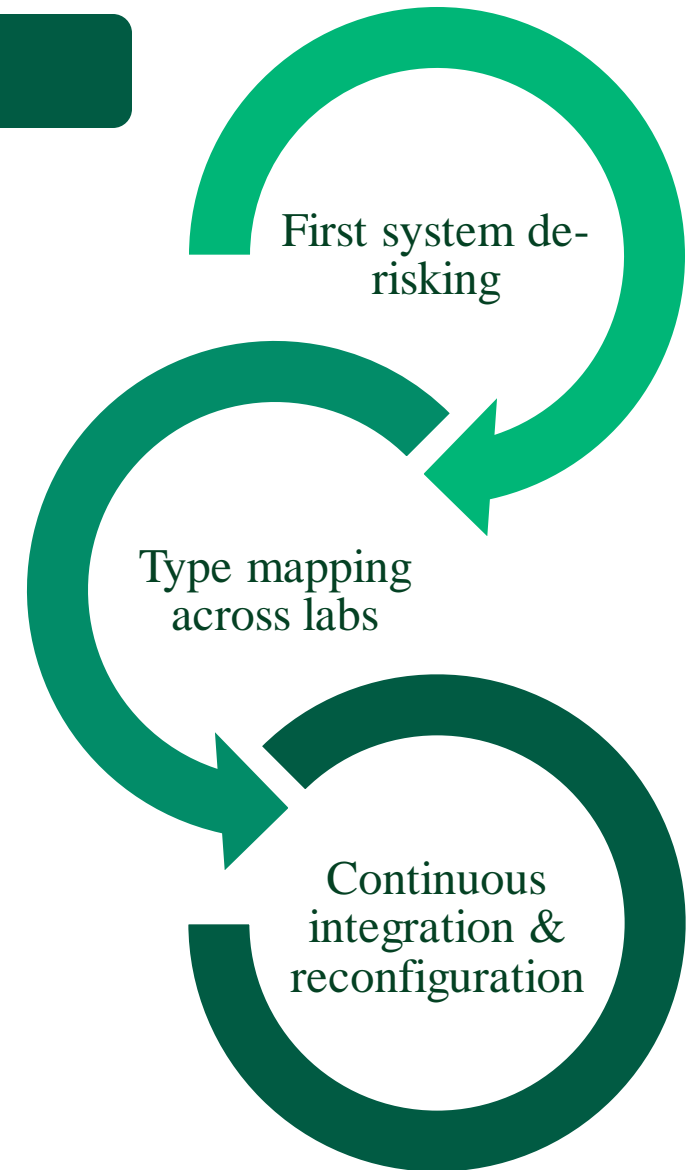
Requirements Mapping

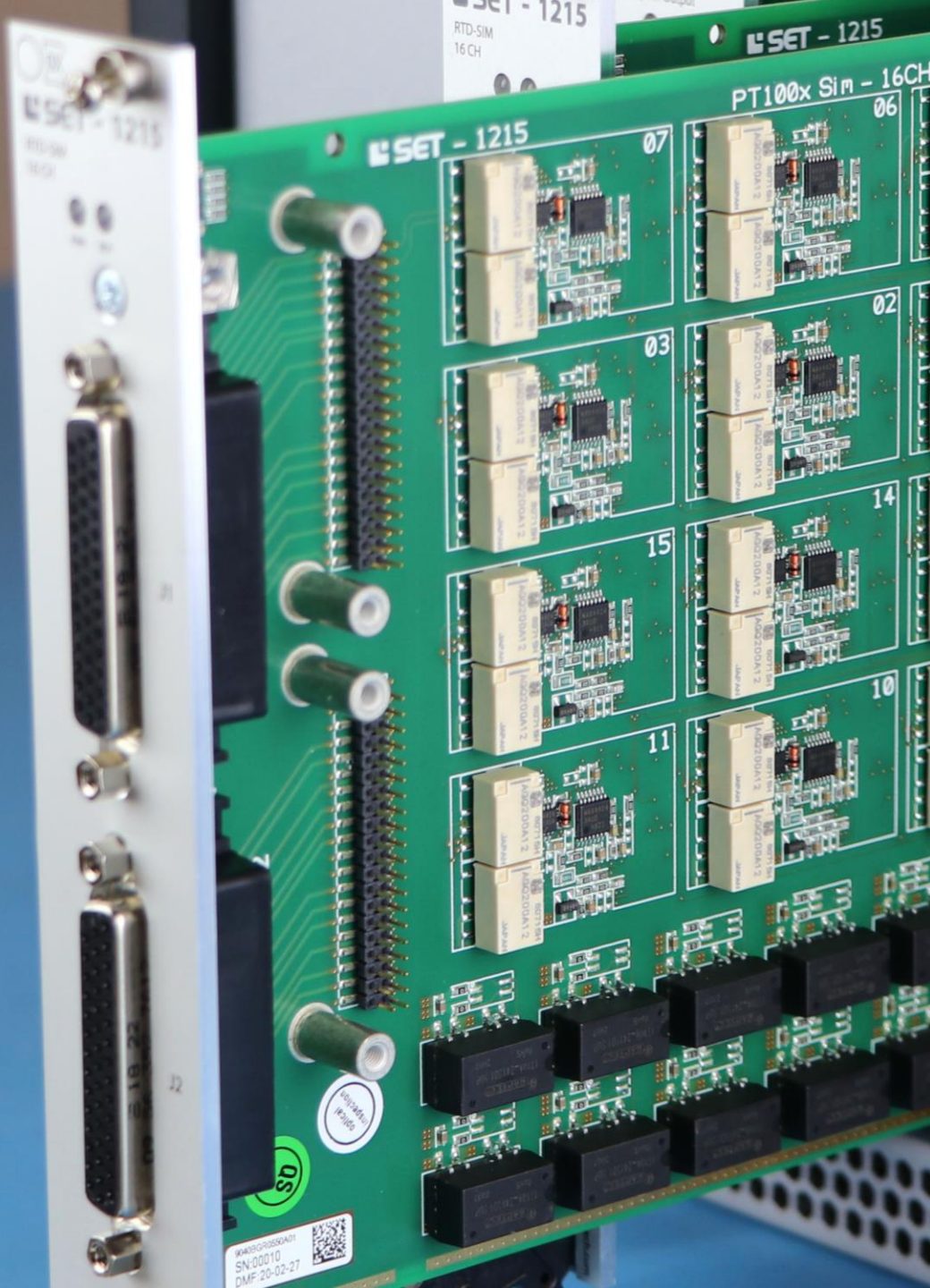
- Product signal types mapped to Tech180 signal types
- New types on past projects can be integrated into standard Tech180 offerings
 - Reduced NRE and de-risking on future test systems



System Reconfiguration

- Commonality of design and type mappings allows for products with similar interfaces to be merged into on test system
- Allows for recapitalization of hardware investments





Summary

- Key benefits of SoD architecture and toolchain
 - 6 Routing Endpoints
 - Simulation
 - Open/Short/Line Fault
 - Load
 - Real/Sim
 - Parallel DAQ
 - Multiplexed Instrumentation
 - Modular Architecture
 - Commercial-Off-The-Shelf (COTS) Components
 - Automated MBSE Workflow
 - Signal Type Library
- Modularity, standardization, and automation allows for rapid development and flexible design



Thank you!

Questions?

Contact Tech180 at info@tech180.us

The background features a dark teal grid of squares. Each square has rounded corners, and semi-circular lines are drawn within the grid, creating a pattern of interlocking shapes. The semi-circles are centered on the grid lines, with some spanning across multiple squares.

™CONNECT